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Renesas Electronics Corporation

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## H8/300H Tiny Series

### Find an Element in a Two-Dimensional Array (ARRAY)

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#### Introduction

Searches a two-dimensional array (hereinafter simply called an array) for an element with the specified value; if a matching element is found, outputs its address, x-index, and y-index.

#### Target Device

H8/300H Tiny Series

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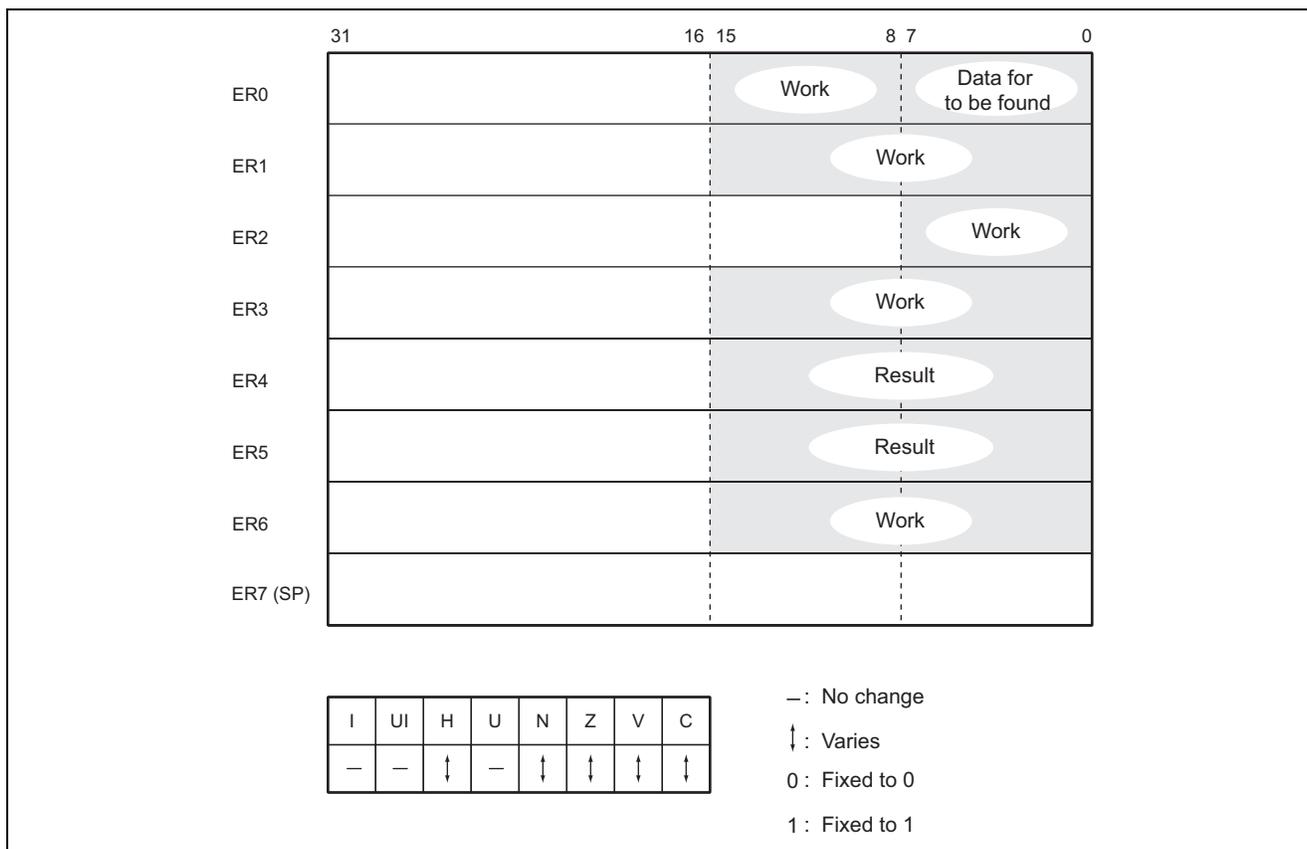
### 1. Function

1. Searches an array for an element with the specified value; if such an element is found, outputs its address, x-index, and y-index.
2. The data to be found is an unsigned 1-byte integer.
3. Array elements are unsigned 1-byte integers.
4. The array should be no larger than 255 bytes × 255 bytes.

### 2. Arguments

Contents		Storage Location	Data Length (Bytes)
Input	Data to be found	R0L	1
	First address of the array	R4	2
	Array size = X (number of columns)	R2L	1
	Array size = Y (number of rows)	R3L	1
Output	Address of the matching data	R4	2
	x-index of the matching data	R5H	1
	y-index of the matching data	R5L	1
	Existence of matching data	C flag (CCR)	—

### 3. Changes to Internal Registers and Flags



#### 4. Programming Specifications

	Program memory (bytes)	
	46	
	-----	
	Data memory (bytes)	
	0	
	-----	
	Stack (bytes)	
	0	
	-----	
	Number of cycles	
	1986	
	-----	
	Re-entrant	
	Yes	
	-----	
	Relocatable	
	Yes	
	-----	
	Interrupts during execution	
	Yes	

#### 5. Notes

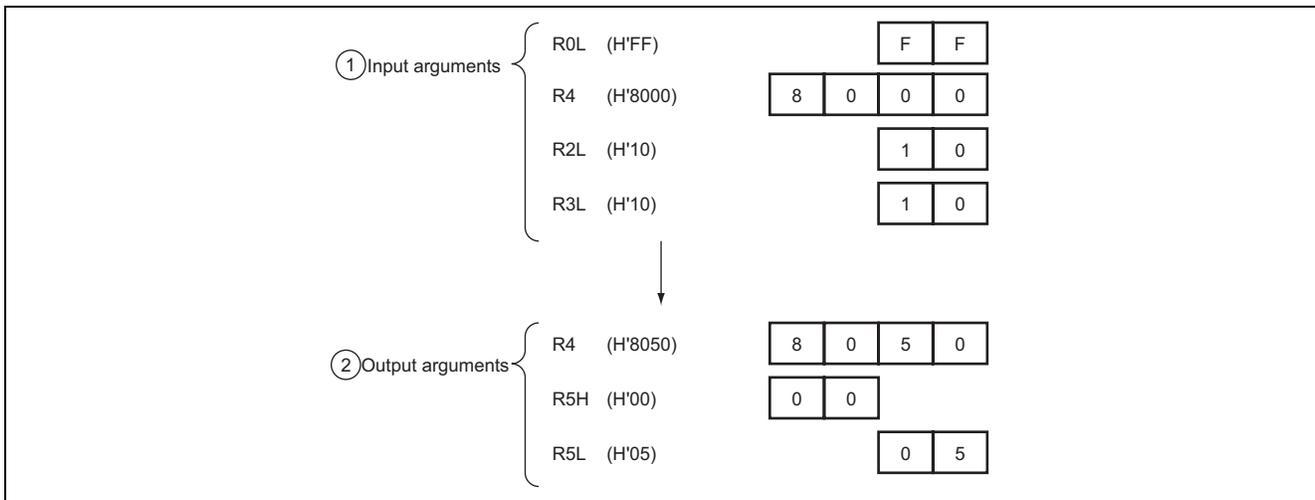
The number of cycles given in the programming specifications is the value for the example of figure 1.

If either of the array-size arguments is 0, execution ends immediately after clearing of the C flag.

## 6. Descriptions

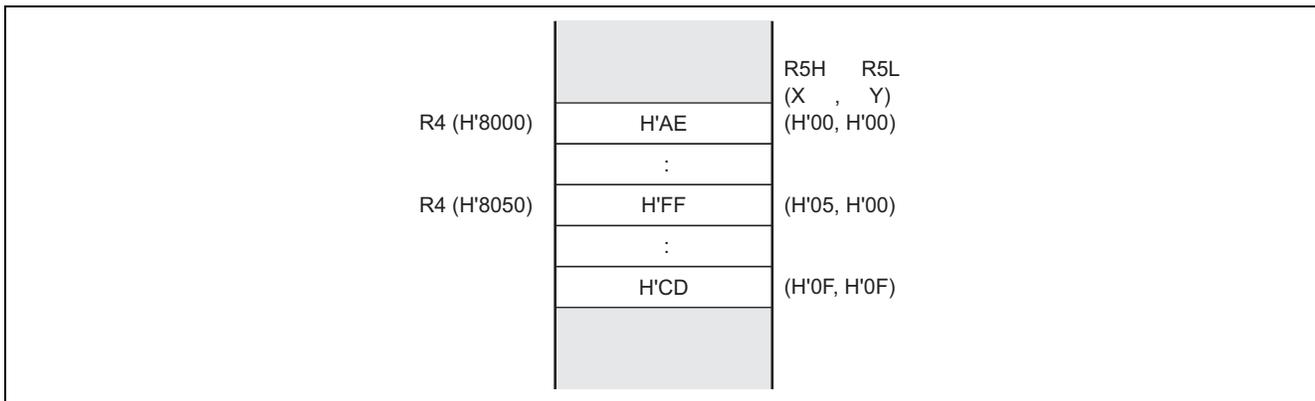
### 6.1 Description of Functions

1. The arguments are listed below.
  - 1) Set the input arguments as below.
    - R0L: data to be found
    - R4: first address of the array
    - R2: array size (X)
    - R3L: array size (Y)
  - 2) The ARRAY subroutine sets the following output arguments.
    - R4: address of the matching data,
    - R5H: x-index of the matching data
    - R5L: y-index of the matching data
- C flag (CCR): indicates the state when the ARRAY subroutine has ended.
  - C flag = 1: Indicates that matching data was found.
  - C flag = 0: Indicates that matching data was not found.
2. Figure 1 illustrates the execution of the ARRAY subroutine. When the input arguments are set as shown, the subroutine searches the array (16 × 16), finds the matching data, then sets its address in R4, x-index in R5H, and y-index in R5L.



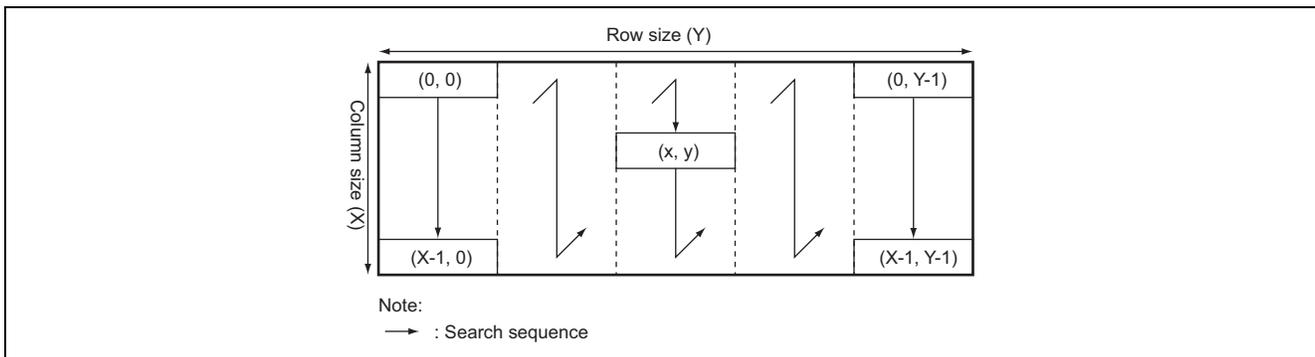
**Figure 1 Example of ARRAY Execution**

3. The execution of ARRAY requires the existence of an array such as that shown in figure 2.



**Figure 2 Array Space**

4. Details of the array are given below with reference to figure 6.3.



**Figure 3 Two-Dimensional Array**

- 1) The size of the array is specified by the numbers of rows (X) and columns (Y).
- 2) An array element is indicated as an x-index and y-index where  $(x, y) = (x^{\text{th}} \text{ row}, y^{\text{th}} \text{ column})$ , with values in the range from (0, 0) to (X-1, Y-1).
- 3) Element (0, 0) is regarded as being at the first address of the array, and the data search follows the sequence shown in figure 3.

## 6.2 Usage Notes

Zero is not specifiable as the column (X) or row size (Y) of an array. If 0 is specified here, the ARRAY subroutine simply clears the C flag in the CCR and ends without searching.

## 6.3 Description of Data Memory

No data memory is used by the ARRAY subroutine.

## 6.4 Example of Usage

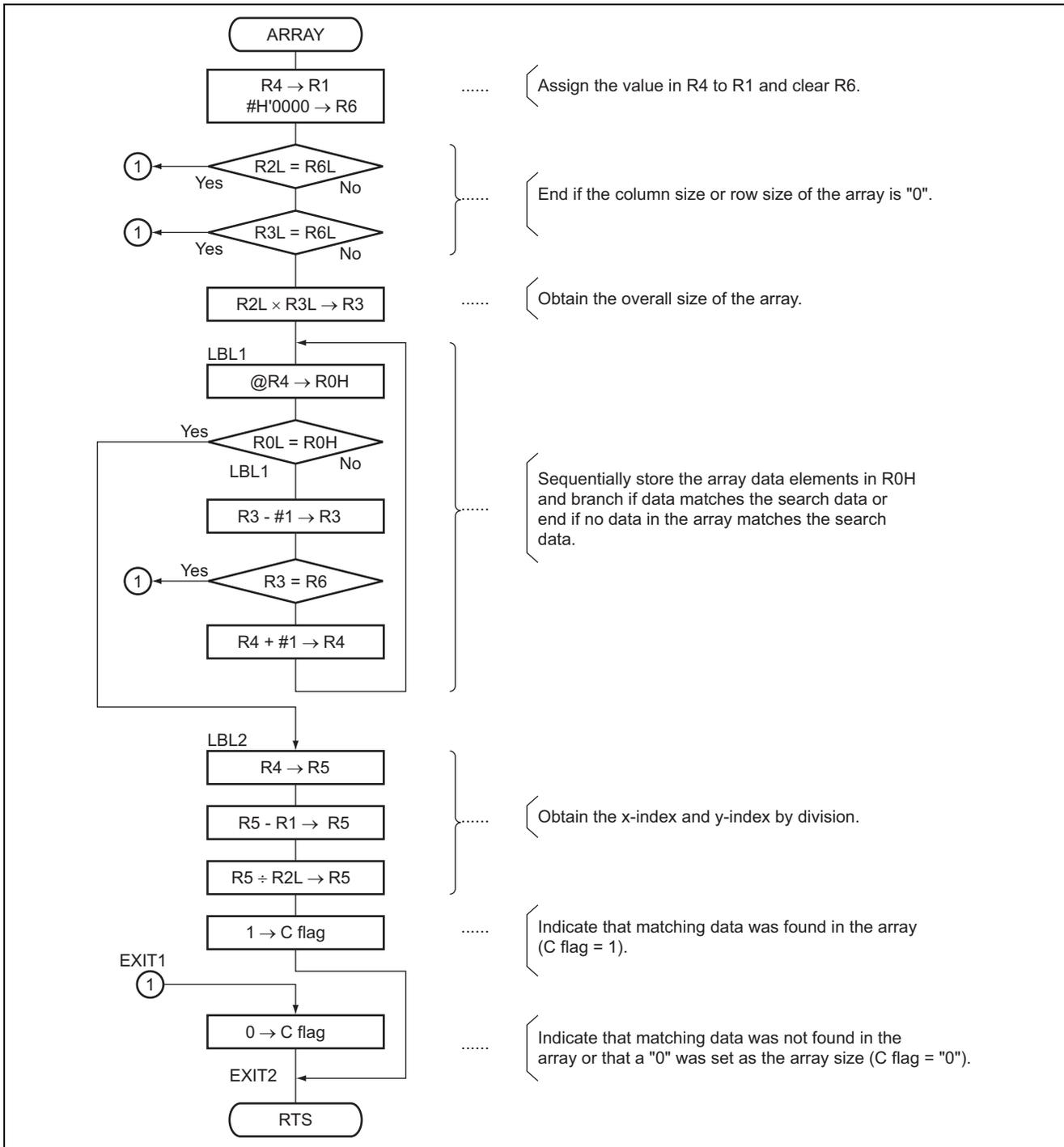
After setting the data to be found, and the first address, column size, and row size of the array, call the ARRAY subroutine.

```

I-WORK1 . RES. W 1      ..... Data memory area for storage of the first address of the array.
I-WORK2 . RES. B 1      ..... Data memory area for storage of the array size (X).
I-WORK3 . RES. B 1      ..... Data memory area for storage of the array size (Y).
I-WORK4 . RES. B 1      ..... Data memory area for storage of the data to be found.
      .
      .
O-WORK1 . RES. W 1      ..... Data memory area where the address of the matching data will be stored.
O-WORK2 . RES. B 1      ..... Data memory area where the x-index of the matching data will be stored.
O-WORK3 . RES. B 1      ..... Data memory area where the y-index of the matching data will be stored.
      .
      .
MOV. B @I-WORK4, R0L    ..... Set the search data.
MOV. W @I-WORK1, R4     ..... Set the first address of the array.
MOV. B @I-WORK2, R2H    ..... Set the array size (X).
MOV. B @I-WORK3, R2L    ..... Set the array size (Y).
JSR @ARRAY              ..... Subroutine call of ARRAY.
MOV. W R4, @O-WORK1     ..... Stores the address of the matched data.
MOV. B R2H, @O-WORK2    ..... Stores the x-index of the matched data.
MOV. B R2L, @O-WORK3    ..... Stores the y-index of the matched data.
      .
      .

```

### 7. Flowchart



### 8. Program Listing

```

1          1          ;*****
2          2          ;*
3          3          ;*      NAME : 2-DIMENSIONAL ARRAY (ARRAY)
4          4          ;*
5          5          ;*****
6          6          ;*
7          7          ;*      ENTRY:  R0L      (REFERENCE DATA)
8          8          ;*      R2L      (NUMBER OF COLUMNS [X])
9          9          ;*      R3L      (NUMBER OF ROWS [Y])
10         10         ;*      R4       (ARRAY START ADDR)
11         11         ;*
12         12         ;*      RETURNS: R5H     (ARRAY ELEMENT: COLUMN INDEX [x])
13         13         ;*      R5L     (ARRAY ELEMENT: ROW INDEX [y])
14         14         ;*      R4      (MATCHING DATA ADDR.)
15         15         ;*      C flag OF CCR (C=1:TRUE , C=0:FALSE)
16         16         ;*
17         17         ;*****
18         18         ;
19         19         .CPU      300HN
20 0000     20         .SECTION ARRAY_code, CODE, ALIGN=2
21         21         .EXPORT  ARRAY
22         22         ;
23         23         ARRAY   .EQU    $          ;Entry point
24 0000 0D41     24         MOV.W   R4,R1
25 0002 79060000 25         MOV.W   #H'0000,R6 ;Clear R6
26 0006 1CAE     26         CMP.B   R2L,R6L
27 0008 4720     27         BEQ     EXIT1    ;Branch to exit if Z=1
28 000A 1CBE     28         CMP.B   R3L,R6L
29 000C 471C     29         BEQ     EXIT1    ;Branch to exit if Z=1
30 000E 50A3     30         MULXU  R2L,R3    ;Get total no. of array elements (R3)
31 0010         31         LBL1
32 0010 6840     32         MOV.B   @R4,R0H    ;Load array data
33 0012 1C80     33         CMP.B   R0L,R0H
34 0014 470A     34         BEQ     LBL2      ;Branch if data found
35 0016 1B03     35         SUBS   #1,ER3    ;Decrement R3
36 0018 1D36     36         CMP.W   R3,R6
37 001A 4710     37         BEQ     EXIT2    ;Branch if false
38 001C 0B04     38         ADDS   #1,ER4    ;Increment data pointer
39 001E 40F0     39         BRA     LBL1     ;Branch always
40 0020         40         LBL2
41 0020 0D45     41         MOV.W   R4,R5
42 0022 1915     42         SUB.W   R1,R5    ;Found data: distance from 1st addr.
43 0024 51A5     43         DIVXU  R2L,R5    ;Get array index [x,y]
44 0026 0401     44         ORC.B   #H'01,CCR ;Set C flag of CCR
45 0028 4002     45         BRA     EXIT2    ;Branch always
46         46         ;
47 002A         47         EXIT1
48 002A 06FE     48         ANDC.B  #H'FE,CCR ;Clear C flag of CCR
49 002C         49         EXIT2
50 002C 5470     50         RTS
51         51         ;
52         52         .END

```

\*\*\*\*\*TOTAL ERRORS 0  
\*\*\*\*\*TOTAL WARNINGS 0

### Revision Record

Rev.	Date	Description	
		Page	Summary
2.00	Feb.28.06	—	Format has been changed from Hitachi version to Renesas version.

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